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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Smith et al.

Docket No.: TI-29811

Serial No.: 09/975,639

Art Unit: 2818

Filed: 10/11/01

Examiner: Hoang, Quoc

Title: Hydrogen Plasma Photoresist Strip And Polymeric Residue Cleanup Process
For Low Dielectric Constant Materials

AMENDMENT UNDER 37 C.F.R. §1.111

July 1, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on <u>7-1-04</u>	
as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450	
<u>Karen Vertz</u> Karen Vertz	<u>7-1-04</u> Date

In response to the Office Action, dated 03/01/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.